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PATENT
Attorney Docket No.: 018865-007400US
Client Ref. No.: 17732.39260

Assistant Commissioner for Patents
Washington, D.C. 20231

On

11/8/02

TOWNSEND and TOWNSEND and CREW LLP

By:

Lisa Kauer

#10/B
Andt
J. Mammillan
11/20/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Ruben Madrid ✓

Application No.: 09/855,820 ✓

Filed: May 14, 2001 ✓

For: CARRIER WITH METAL BUMPS
FOR SEMICONDUCTOR DIE
PACKAGES

Examiner: E. Wojciechowicz

Art Unit: 2811

ELECTION AND SUPPLEMENTAL
AMENDMENT

TECHNOLOGY CENTER 2800

NOV 19 2002

RECEIVED

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed October 22, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-3, 5-10, 12-23, and 28. ✓

Please amend claim 27 as follows:

27. (Amended) The method of claim 26 wherein attaching comprises:
attaching the semiconductor die to a die attach region of the carrier, and wherein the plurality of bumps is disposed around the semiconductor die.